

Patent

Customer No.: 31561
Docket No.: 10073-US-PA
Application No.: 10/707,609

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chen et al.
Application No. : 10/707,609
Filed : 2003/12/24
For : FLIP CHIP PACKAGE STRUCTURE
Art Unit : 2814
Examiner : Trinh, Vikki H.

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TRANSMITTAL LETTER

002-1-571-273-8300

(Via fax : 1+2+9 pages)

Assistant Commissioner for Patents
Alexandria, VA 22314.

Dear Sir,

In response to the Office Action dated May 3, 2005(Paper No.: 0405), please find the Response to Office Action, in 9 pages.

I believe that no fee is incurred. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10073-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date : August 2, 2005

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